

BF 1608 Series

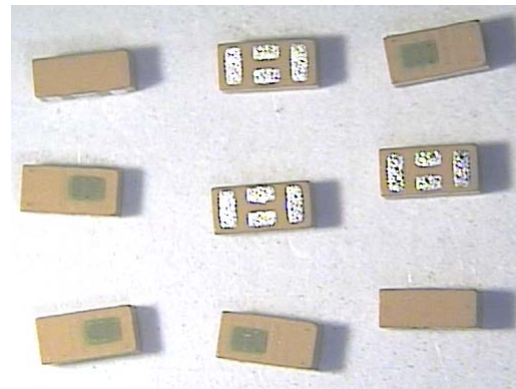
Multilayer Chip Band-Pass Filters

Features

- ❖ Ultra small SMD type with low loss at pass-band and high attenuation at stop-band.
- ❖ HF & RoHS Compliant

Applications

- ❖ Mobile communication systems.



Specifications

Part Number	Frequency Range (MHz)	Insertion Loss @ BW (dB)	VSWR @BW	Frequency (MHz)	Attenuation (dB)
BF1608-L1R9NDC_	1805 ~ 2025	2.1 max.@ 25°C 2.4 max.@-40~105°C	2.0 max.	700~950 MHz	30 min.
				950~1050 MHz	15 min.
				2400~2500 MHz	35 min.
				2700~5150 MHz	35 min.
				5150~5850 MHz	35 min.
				5850~12750 MHz	32 min.

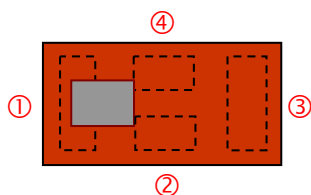
Q'ty/Reel (pcs) : 4000
 Operating Temperature Range : -40 ~ +105 °C
 Storage Temperature Range : -40 ~ +105 °C
 Storage Period : 12 months max.*
 *12 months in vacuum sealed bag and 1 week after opened. Please keep unused parts in vacuum sealed bags.
 Solder Paste : SAC 305 type is recommended.
 Power Capacity : 3W max.

Part Number

BF 1608 - L 1R9 NDC □ /LF
 ① ② ③ ④ ⑤ ⑥ ⑦

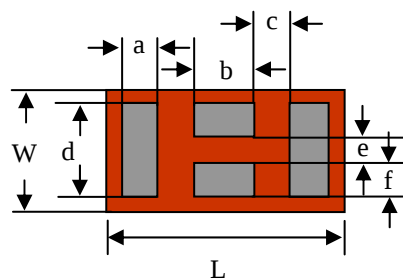
① Type	BF : Band-Pass Filter	② Dimensions (L × W)	1.6 × 0.8 mm
③ Material Code	L	④ Frequency Range	1R9=1900MHz
⑤ Specification Code	NDC	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	/LF=lead-free		

Terminal Configuration



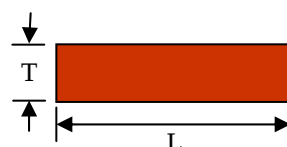
No.	Terminal Name	No.	Terminal Name
①	IN/OUT	③	IN/OUT
②	GND	④	GND

Dimensions and Recommended PC Board Pattern



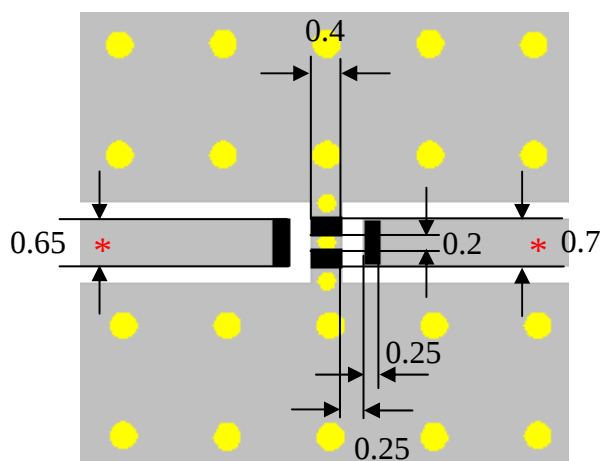
< Bottom View >

Unit: mm



< Side View >

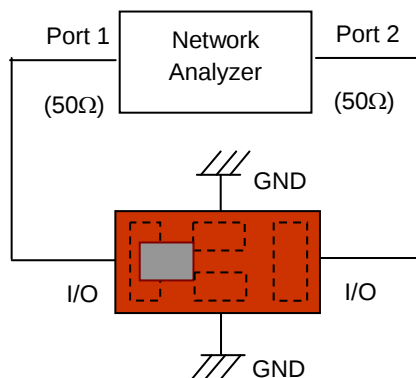
Mark	L	W	T	a	b	c	d	e	f
Dimensions	1.6 ± 0.15	0.8 ± 0.15	0.7 Max.	0.25 ± 0.05	0.40 ± 0.1	0.23 ± 0.1	0.55 ± 0.1	0.21 ± 0.05	0.20 ± 0.05



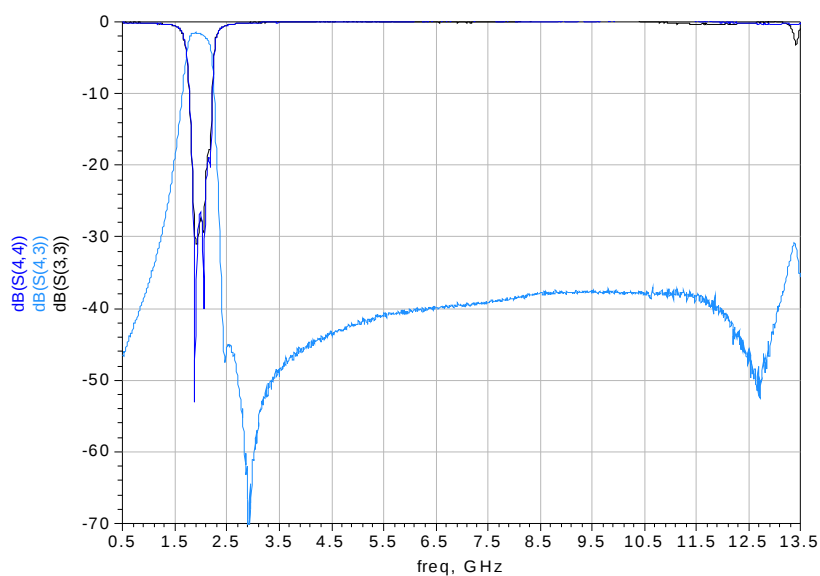
-  Solder Resist
-  Land
-  Through-hole (ϕ 0.3, 0.23)

* Line width should be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness.

Measuring Diagram



Typical Electrical Characteristics (T=25°C)

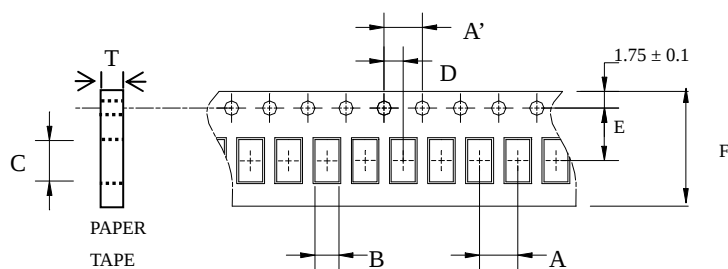


Notes

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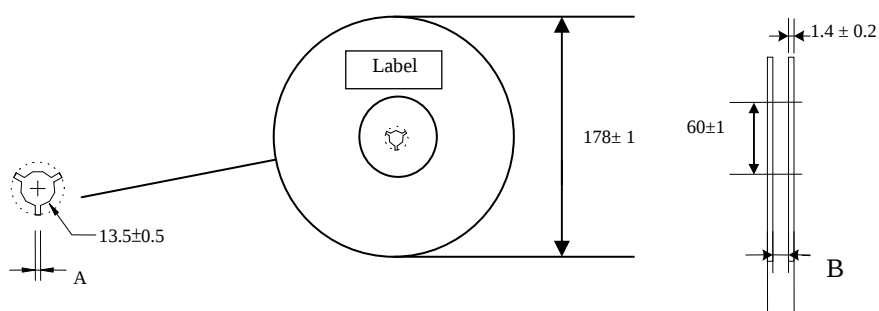
Taping Specifications

❖Tape Dimensions (Unit: mm) & Quantity



Type	A	A'	B	C	D	E	F	T	Quantity/reel	Tape material
1608	4.0±	4.0±	1.10±	1.92±	2.0±	3.5±	8.0±	0.75±	4,000pcs	Paper
	0.1	0.1	0.1	0.1	0.1	0.1	0.1	0.05		

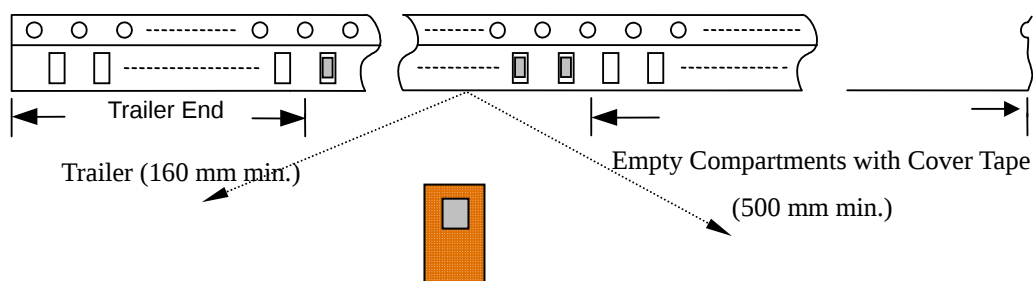
❖Reel Dimensions (Unit: mm)



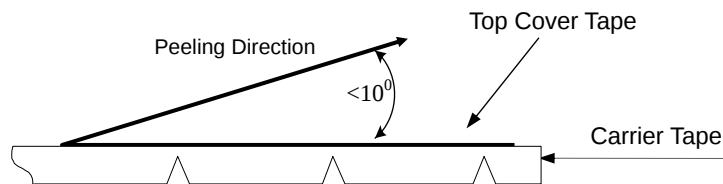
Label: Customer's Name,
ACX P/N, Q'ty, Date,
ACX Corp.

Type	A	B
1608	2.3±0.5	9.0±0.3

❖Leader and Trailer Tape



❖ **Peel-off Force**



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of 300±10 mm/min .

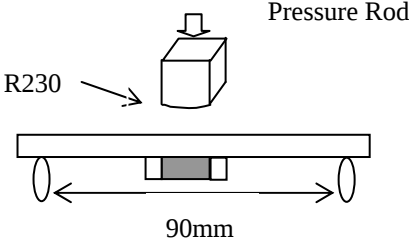
❖ **Storage Conditions**

- (1) Temperature: 5 ~35°C , relative humidity (RH): 45~75%.
- (2) Non-corrosive environment.

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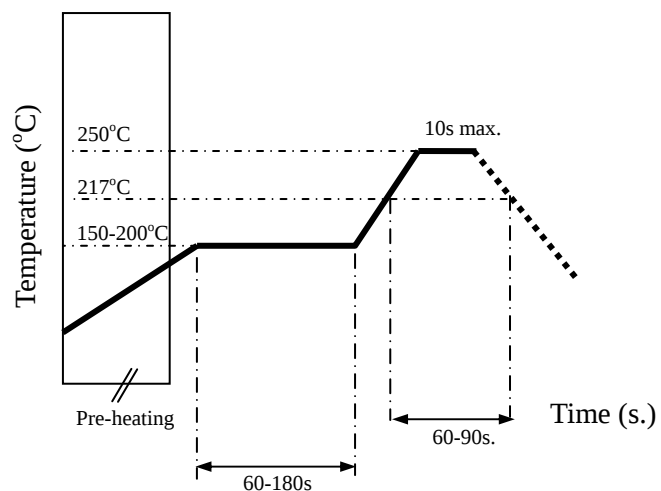
Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	1. No apparent damage 2. More than 75% of the terminal electrode shall be covered with new solder	1. Preheat: $120 \pm 5^{\circ}\text{C}$ 2. Solder: $245 \pm 5^{\circ}\text{C}$ for 5 ± 1 sec
Soldering strength (Termination Adhesion)	1. 10N minimum	1. Solder specimen onto test jig. 2. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction
Deflection (Substrate Bending)	1. No apparent damage 2. Fulfill the electrical specification	1. Solder specimen onto test jig (FR4, 1.6mm) using the recommend soldering profile. 2. Apply a bending force of 2mm deflection 
Heat/Humidity Resistance	1. No apparent damage 2. Fulfill the electrical specification after test	1. Temperature: $85 \pm 2^{\circ}\text{C}$ 2. Humidity: 90% ~ 95% RH 3. Duration: 1000 ± 48hrs 4. Recovery: 1-2hrs
Thermal shock (Temperature Cycle)	1. No apparent damage 2. Fulfill the electrical specification after test	1. One cycle/step 1 : $125 \pm 5^{\circ}\text{C}$ for 30 min step 2 : $-40 \pm 5^{\circ}\text{C}$ for 30 min 2. No of cycles : 100 3. Recovery: 1-2 hrs
Low Temperature Resistance	1. No apparent damage 2. Fulfill the electrical specification after test	1. Temperature: $-40 \pm 5^{\circ}\text{C}$ 2. Duration: 500 ± 24hrs 3. Recovery: 1-2hrs

Soldering Conditions

❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



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